

ON Semiconductor **10/15/2019**

Base Part		FQPF27N25		
Orderable Part		FQPF27N25		Total weight (mg) 2112.34
Homogenous Material	Weight (mg)	Substance in Mat.	CAS #	% Avg. Weight
Die	13.5	Silicon (Si)	7440-21-3	100
Die Attach	4.01	Silver (Ag)	7440-22-4	1.5
		Lead (Pb)	7439-92-1	93.5
		Tin (Sn)	7440-31-5	5
Lead Frame	1294.26	Tin (Sn)	7440-31-5	0.10000309
		Copper (Cu)	7440-50-8	99.89999691
Mold Compound-Black	784.93	2,6-dibromo-4-[1-(3-bromo-4-hydroxyphenyl)-1-methylethyl]phenol	6386-73-8	2.99389755
		Ortho Cresol Novolac Resin	29690-82-2	20.0017836
		Antimony Trioxide (Sb2O3)	1309-64-4	2.49703795
		Carbon Black (C)	1333-86-4	0.99996178
		Fused Silica (SiO2)	60676-86-0	73.50731912
Plating	13.2	Tin (Sn)	7440-31-5	100
Wire Bond - Al	2.44	Aluminum (Al)	7429-90-5	100

Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the most accurate information, we cannot guarantee to its accuracy since the data has been compiled based on the ranges provided, and some information provided by the subcontractors and raw material suppliers may have been withheld to protect their business proprietary information. Thus this information is provided only as estimates, and do not include trace levels fo dopants and metal materials contained within silicon devices in the finished products. There is no intentional use of Mercury, Hexavalent Chromium, Cadmium, PBB or PBDE (5 of the 6 RoHS banned substances) in this or any of our other products. For further explanation on material composition calculations, please view our Product Chemical Content Brochure at:

<http://www.onsemi.com/pub/Collateral/BRD8022-D.PDF>